

REINFORCED DIE PAD SUPPORT STRUCTURE
ABSTRACT OF THE INVENTION

[0034] A semiconductor package comprising a die pad defining opposed top and bottom surfaces and a peripheral edge. Attached to the peripheral edge of the die pad is a plurality of support feet which extend downwardly relative to the bottom surface thereof. A plurality of leads extend at least partially about the peripheral edge of the die pad in spaced relation thereto. Attached to the top surface of the die pad is a semiconductor die which is electrically connected to at least one of the leads. A package body encapsulates the die pad, the support feet, the leads and the semiconductor die such that at least portions of the leads are exposed in the package body.